

IN THE ABSTRACT

The current Abstract should be canceled and the following submitted in its place.

A method of forming a stencil for the manufacture of semiconductor devices includes defining a plurality of slightly spaced segmental annular openings in a stencil plate. The spacing between the segmental annular openings define spokes extending from a central portion of said stencil connected via those spokes to the rest of the stencil plate. The spokes extend past two adjacent annular segments.

~~A Z-axis electrical contact may be formed using a resinous deposit containing conductive particles which may align along surface regions to form an electrical conduction path over the resinous material. If the resinous material is thermoplastic, the material may be heated to mechanically bond to contact surfaces. Advantageously, the resinous material may be formed by forcing a resinous matrix containing conductive particles through an annular opening in a stencil. The resulting member allows surfaces to be contacted which may be irregular or may be covered by native oxide layers.~~